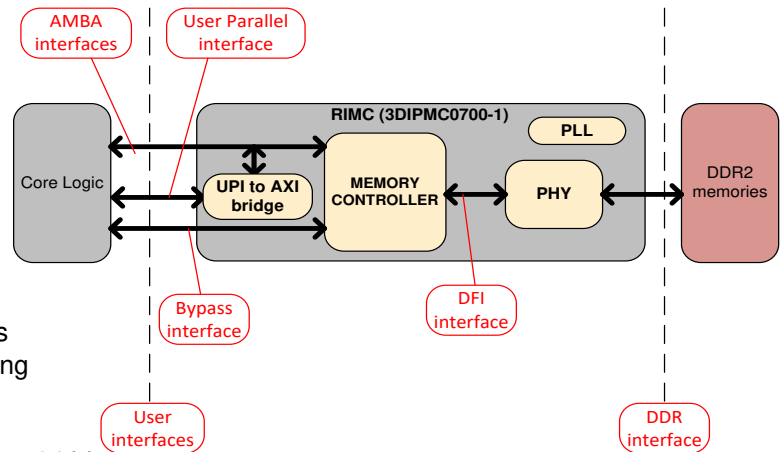


1 FEATURES

- Configurable via AMBA compliant (AXI/AHB/APB) user interface
- DFI 2.1 compliant DDR PHY interface
- Provides rank and bank management algorithms
- Dynamically configurable via an 8-bit APB slave interface
- Controller Bypass mode provides direct access to memories
- Selectable Hamming or Reed-Solomon Error Correction Code (ECC)
- Configurable DDR2 ranks to increase memory capacity
- Clock & ODT settings compatible with 3D PLUS modules
- Selectable Burst-of-4 or Burst-of-8 accesses
- Selectable Enable/Disable of DDR2 scrubbing
- User-definable scrubbing frequency
- Selectable DRAM refresh time
- Configurable user data width: x8, x16, x32 or x64 bits



2 OVERVIEW

The Radiation Intelligent Memory Controller (RIMC) is a fully configurable DDR2 SDRAM memory controller IP core designed to work with 3D PLUS DDR2 memory modules to achieve improved radiation tolerance. The RIMC contains all of the standard functions of a DDR memory controller for data width applications from 8b up to 64b, and additional functions, including Single Event Upset (SEU) mitigation and Single Event Functional Interrupt (SEFI) protection (later described in paragraph 4.2) to be able to work in radiation environments.

In addition to the memory controller IP within the RIMC IP core, the user can optionally select any of a number of 3D PLUS provided PHY IP or the user can develop their own PHY IP.

The RIMC has two primary interfaces, the user interface (UIF) and the DDR memory interface (DIF).

The UIF is comprised of at least one AHB bus, AXI bus or MIG, and also contains an APB bus for user dynamic configuration:

- Slave APB interface dedicated to internal registers
- Optional slave AHB/AXI interface
- Optional Xilinx MIG interface
- Optional Bypass interface

The Memory Controller is defined by the previously described UIF and the DIF, compliant to DFI 2.1, to send commands and data to the DDR memory components through the DDR PHY (which is uniquely configured to work with specific FPGAs/ASICs).

Table Of Content

1	FEATURES	1
2	OVERVIEW	1
3	RIMC CONFIGURATION	5
4	MEMORY CONTROLLER.....	6
4.1	Clock, Reset and Initialization	6
4.2	Error management	7
4.2.1	Error Correction Code (ECC)	7
4.2.2	Scrubbing functionality	9
4.2.3	SEFI Protection	9
4.3	RIMC interfaces	9
4.3.1	AMBA interfaces.....	10
4.3.2	Bypass interface.....	12
4.3.3	DFI interface.....	12
4.4	Memory Controller generics/parameters and ports	12
4.5	Memory Controller registers	17
5	RIMC (MEMORY CONTROLLER + PHY)	20
5.1	RIMC interfaces	20
5.1.1	DDR2 interface.....	20
5.1.2	Xilinx MIG interface	20
5.2	RIMC generics/parameters and ports	20
6	RIMC PERFORMANCES.....	26
6.1	Maximum frequency.....	26
6.2	IP size	27
7	DELIVERABLES	28
8	TARGET COMPATIBILITY.....	28
9	PART NUMBER / ORDER INFORMATION	29
10	REVISION HISTORY.....	30

TABLES and FIGURES

Table 1: Frequency ratio generics configuration.....	7
Table 2: Supported ECC codes	8
Table 3: 3D PLUS DDR2 modules.....	8
Table 4: Memory Controller Core Ports	12
Table 5: Memory Controller AMBA Ports.....	13
Table 6: Memory Controller DFI Ports	14
Table 7: Memory Controller Bypass Ports	15
Table 8: Memory Controller Generic/Parameter list.....	17
Table 9: RIMC registers list.....	17
Table 10: ECC_DErr_Reg0 (Most Significant Byte) and ECC_DErr_Reg1 (Least Significant Byte)	18
Table 11: ECC_SErr_Reg0 and ECC_SErr_Reg1	18
Table 12: ECC_DErr_Clr register.....	18
Table 13: ECC_SErr_Clr register.....	18
Table 14: Bypass_Reg register.....	18
Table 15: Init_Pad_Reg register	18
Table 16: Init_Pad_Sts register.....	18
Table 17: Init_Pad_Ctl register.....	19
Table 18: ScrubEn_Reg register.....	19
Table 19: Scrubbing_Reg0 and Scrubbing_Reg1	19
Table 20: Scrub_Ctl register	19
Table 21: ScrubAd_Sts0 to ScrubAd_Sts3.....	19
Table 22: CorEn_Reg register	19
Table 23: CorVec_Reg0 to CorVec_Reg11	19
Table 24: CorBeat_Reg	19
Table 25: RIMC Core Ports.....	21
Table 26: RIMC AMBA Ports	21
Table 27: RIMC DDR Ports.....	21
Table 28: RIMC MIG ports	22
Table 29: RIMC Bypass Ports.....	23
Table 30: RIMC Generic list.....	25
Table 31: Xilinx resource usage.....	27
Table 32: Microsemi RTG4 resource usage	27



Radiation Intelligent Memory Controller DDR2 SDRAM Controller IP Core 3DIPMC0700-1

Figure 1: Embedded clock management	6
Figure 2: nCK_PER_CLK values	6
Figure 3: Interfaces with DDR controller	10
Figure 4: Configuration management	10
Figure 5: Directory architecture of the deliverables	28

3 RIMC CONFIGURATION

To use the RIMC to access 3D PLUS DDR2 Memory modules, it must first be setup by writing data to dedicated RIMC configuration registers. This paragraph describes the flow to configure these parameters in the RIMC and how to build RIMC initialization circuitry.

Memory Setting

The Memory Setting configuration data are dependent on the 3D PLUS memory modules' characteristics, which can be found within 3D PLUS's memory module Detail Specifications. Below are the items that should be configured.

- The burst length (BURST_LEN generic) shall be set to select either a Burst-of-4 or a Burst-of-8
- The user data bus width (DATA_WIDTH generic) should be selected by the application, and the ECC width (ECC_WIDTH generic) should be selected in accordance with paragraph 4.2.1;
- The number of control signals, ranks, banks and rows shall be configured per Table 30.

The other configuration data are dependent on the end-user's application.

Clock Frequency

The Clock should be configured in accordance with paragraph 4.1;

Error Management

Error Management should be configured in accordance with paragraph 4.2; Below are the items which should be configured.

- ECC setting
- Scrubbing setting
- SEFI protection setting

Interface Setting

Interface Setting should be configured in accordance with paragraph 4.3. Below are the items which should be configured.

- Core logic Interface AXI/AHB/APB
- DFI Interface
- Bypass mode (Direct DDR2 Access)
- Uncorrectable errors Interruption

4 MEMORY CONTROLLER

In addition to all of the standard functions of an Synchronous DRAM memory controller, the Memory controller contains the functions described in the following paragraphs.

The RIMC IP is responsible for the following standard functions:

- Bank management
- Conversion of user AMBA commands to DFI compatible DDR commands.

The RIMC IP also embeds the following additional functions:

- Data error management including an ECC and a scrubbing mechanism;
- SEFI detection and correction mechanisms;

4.1 CLOCK, RESET AND INITIALIZATION

The RIMC needs 3 internal clocks. The first clock, SysClk, is dedicated to the Memory Controller as well as the AMBA user interfaces. The second clock, DFIClk, is dedicated to the DFI interface. These 2 clocks shall be synchronous with a frequency ratio of 1:1, 2:1 or 4:1 (nCK_PER_CLK). The third clock has a 200MHz fixed frequency, and is used for the Xilinx PHY only (this clock is not requested for RTG4).

DFIClk and SysClk are generated by an RIMC embedded PLL from ClkIn.

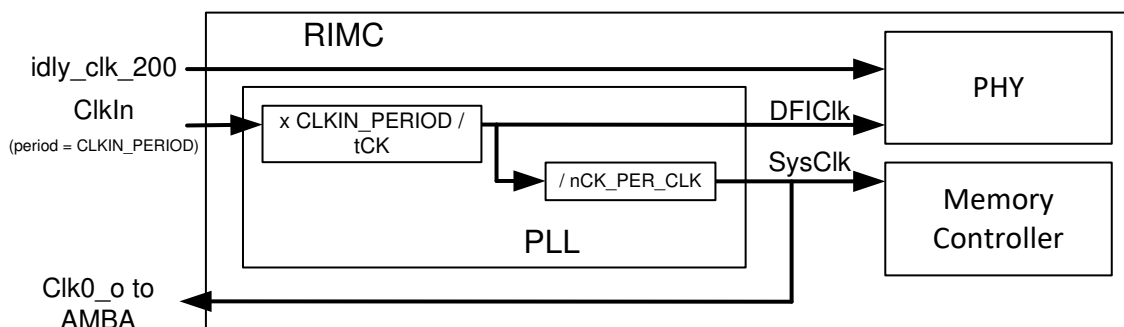


Figure 1: Embedded clock management

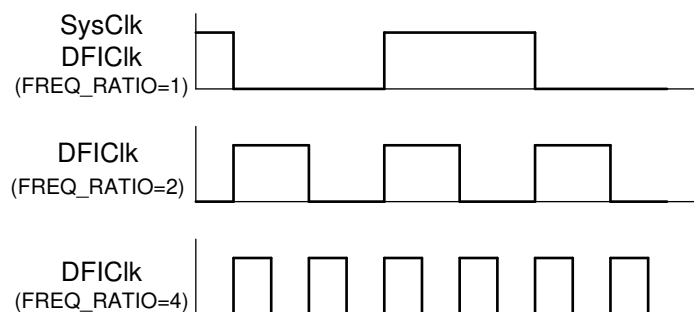


Figure 2: nCK_PER_CLK values

FPGA Type	nCK_PER_CLK
Xilinx V5	1, 2, 4
Xilinx 7-series	2, 4
Microsemi RTG4	1, 2, 4

Table 1: Frequency ratio generics configuration

One asynchronous input reset (Rst_N) must be provided.

After deassertion of the reset input port (Rst_N), the RIMC automatically configures itself by reading the following configuration input pins:

- SCRUB_EN: This input port can enable or disable the scrubbing mechanism. When activated the scrubbing performs read and write accesses across the entire memory array after the initialization phase has been completed.
- REF_MODE: This input port is used to select 32ms or 64ms refresh time

After this automatic configuration process, the user may dynamically update the internal configuration using the APB slave interface.

A memory initialization sequence is recommended after powering up the User Memory, and this initialization sequence can be enabled through the INIT_Pad APB register. When enabled, the RIMC IP Core initializes the entire memory array with a fixed value as soon as the Physical layer is ready (after the completion of the Power-up sequence and calibration phase). The Byte value to be written to the entire memory array is contained in the Init_Reg register.

If the initialization phase is not performed and a Read is requested by the user to an address prior to a Write at the same address, the RIMC IP Core may detect potential ECC errors.

4.2 ERROR MANAGEMENT

4.2.1 ERROR CORRECTION CODE (ECC)

The RIMC SEU mitigation scheme uses different configurable ECCs (Hamming or Reed-Solomon) and scrubbing to correct SEUs and Single Event Row Errors (SERE). For example, using a Reed-Solomon code for 32b data and 50% overhead [2 * RS(6;4), m=4, Global Bus = 48bits], the RIMC can correct up to 8 bits of error (row error) in one die per 48b, and 2 SEUs in the same address of different dice per 48b. In cases where scrubbing is applied, the worst case (in which one particle creates 2 upsets in 2 dice) error rate will be 3.8E-9 upset/day/module.

The RIMC implements an Error Correction Code (ECC) with additional DDR2 components. The supported configurations are described in Table 2.

Two different ECC types are handled by the RIMC:

- Hamming, which is able to mitigate SEU
- Reed-Solomon, which is able to mitigate SEU, MBU and SERE.

DDR2 Component Width	User Data Bus Width (generic DATA_WIDTH)	ECC Bus Width (generic ECC_WIDTH)	Global Bus Width (DQ_WIDTH = DATA_WIDTH+ECC_WIDTH)	ECC onfiguration
8	8	0	8	No ECC
8	8	5	16	Hamming 8+5 ⁽¹⁾
8	16	0	16	No ECC
8	16	6	24	Hamming 16+6 ⁽¹⁾
8	16	16	32	2*RS(6;4) with m=4
8	32	0	32	No ECC
8	32	7	40	Hamming 32+7 ⁽¹⁾
8	32	16	48	2*RS(6;4) with m=4
8	64	0	64	No ECC
8	64	32	96	4*RS(6;4) with m=4
16	16	0	16	No ECC
16	32	0	32	No ECC
16	32	32	64	4*RS(4;2) with m=4
16	64	8	72	Hamming 64+8 ⁽¹⁾
16	64	32	96	4*RS(6;4) with m=4

Table 2: Supported ECC codes

Note 1: This ECC utilizes a Hamming code. This code CANNOT correct for a DDR2 component failure but it is able to correct a SEU.

To use this feature additional DDR2 components are added in parallel (data path increased) on the board.

The RIMC can be used with 8-bit and 16-bit DDR2 component widths.

Below is a list of available 3D PLUS DDR2 modules with their configurations:

DDR II P/N	Density	Configuration	Access/Clock	Package
3D2D1G08US1285	1G	128M x 8	200-333Mhz	SOP74
3D2D2G08US2662	2G	256M x 8	200-333Mhz	SOP74
3D2D2G16UB2684	2G	128M x 16	200-333Mhz	BGA95
3D2D4G08US4661	4G	512M x 8	200-333Mhz	SOP74
3D2D4G72UB3652	4G	64M x 72	200-333Mhz	BGA191
3D2D6G48UB3687	6G	128M x 48	200-333Mhz	BGA143
3D2D6G48UQ3694	6G	128M x 48	200-333Mhz	QFP144
3D2D8G08US8663	8G	1G x 8	200-333Mhz	SOP88

Table 3: 3D PLUS DDR2 modules

4.2.2 SCRUBBING FUNCTIONALITY

A scrubbing mechanism can be dynamically enabled with the SCRUB_EN input pin or the ScrubEn_Reg register.

When enabled, the RIMC IP core periodically reads the entire memory array and then writes the corrected data back into the memory array. The frequency of the scrubbing is user-defined through the Scrub_Reg register.

An Example of Scrub_Reg configuration:

- The RIMC is connected to a single 3D2D6G48UB3687 (BGA package) or a single 3D2D6G48UQ3694 (QFP package) organized as 128M x 48bits
- User wants to scrub the full memory array in 60 seconds (t).
- DFIClk frequency (F_{DFI}) is 266 MHz
- Burst length is set to 8

$Scrub_Reg = BURST_LENGTH * t * F_{DFI} / 128M = 953$ clock cycles

In this example the RIMC performs one Read/Write Burst every 953 clock cycles.

4.2.3 SEFI PROTECTION

Traditionally, SEFI mitigation has involved power cycling after the occurrence of a SEFI; however, power cycling will lead to data loss. To avoid data loss, a specific SEFI protection technique has been designed in the RIMC IP Core to prevent SEFI and to replace the traditional power cycling strategy. This SEFI protection is integrated in the RIMC IP core and is transparent to the user. Verification tests have been performed to confirm the robustness of this protection IP, and no SEFI were observed up to $LET > 60 \text{Mev-cm}^2/\text{mg}$.

To configurate the device SEFI protection, the Bypass_Reg register should be configured as below:

b00: SEFI protection set to Strong Level
b01: SEFI protection set to Simple Level
b10: Switch off the SEFI protection

4.3 RIMC INTERFACES

The RIMC is defined by three interfaces (see Figure 3):

- The AMBA interface
- The Direct DDR Access interface
- The DDR PHY interface, compliant to DFI 2.1

These three interfaces are described in the following paragraphs.

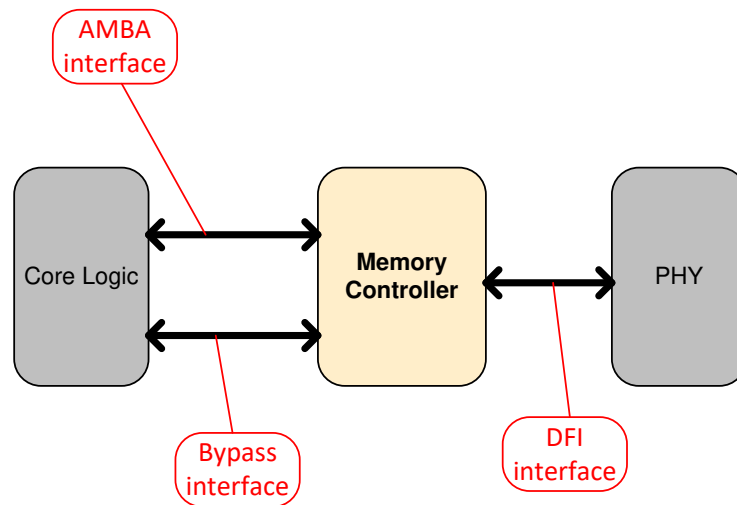


Figure 3: Interfaces with DDR controller

4.3.1 AMBA INTERFACES

Three AMBA interfaces are available for connection to the Memory Controller:

- AMBA AXI: 0 to 8 ports can be instantiated through the NB_AXI_SLV generic.
- AMBA AHB: 0 to 8 ports can be instantiated through the NB_AHB_SLV generic
- AMBA APB: This interface is used to configure the IP.

At least one port shall be instantiated to be synthesizable, i.e. $NB_AXI_SLV + NB_AHB_SLV \geq 1$

The Memory Controller can be configured by the core logic using the slave APB interface dedicated to internal registers.

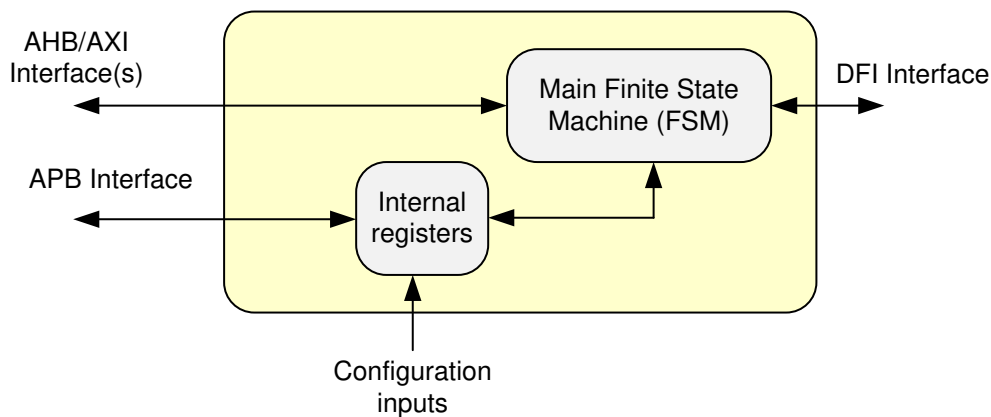


Figure 4: Configuration management

4.3.1.1 AXI interface

The Memory Controller is compliant to the AMBA Advanced eXtensible Interface (AXI) protocol. Up to 8 slaves AXI interfaces can be instantiated inside the RIMC through the NB_AXI_SLV generic.

The data bus width of both the write channel and the read channel can be configured to 16, 32, 64, 128 or 256 bits.

Note: To realize optimal bandwidth, AXI data width should be greater than or equal to “DDR data bus” width * 2 * nCK_PER_CLK.

The key features of the AXI protocol are:

- separate address/control and data phases
- support for unaligned data transfers using byte strobes
- burst-based transactions with only start address issued
- separate read and write data channels to enable Direct Memory Access (DMA)
- ability to issue multiple outstanding addresses
- out-of-order transaction completion
- easy addition of register stages to provide timing closure.

4.3.1.2 AHB interface

The Memory Controller is compliant with AHB slave interface data widths of 16, 32, 64, 128 and 256 bits.

*Note: To realize optimal bandwidth, AHB data width should be greater than or equal to “DDR data bus” width * 2 * nCK_PER_CLK.*

The AHB slave interface provides the following input signals for each AHB port:

- HSEL: Slave select
- HADDR: Address bus
- HWRITE: Transfer direction (0 for Read / 1 for Write)
- HTRANS: Transfer type
- HSIZE: Transfer size
- HBURST: Burst type
- HWDATA: Write data bus
- HPROT: Protection control. This signal is not used by RIMC IP Core
- HREADY: Transfer done
- HMASTER: Master number. This signal is not used by RIMC IP Core
- HMASTLOCK: Locked sequence

The AHB slave interface provides the following output signals for each AHB port:

- HREADY: Transfer done
- HRESP: Transfer response
- HRDATA: Read data bus
- HSPLIT: Split completion request. The RIMC does not implement the SPLIT functionality so this output is driven LOW.

The slave AHB accepts the following burst types:

- SINGLE
- INCR4
- INCR8
- INCR16

The Memory Controller implements neither the RETRY nor the SPLIT functions. The Memory Controller does not implement the BURST with an unknown number of beats.

An HRESP_ERROR is generated by the RIMC in the following cases:

- The DDR2 memory array is not initialized
- An uncorrectable error is detected during a Read operation.
- An AHB address is out of the DDR2 address range

4.3.1.3 APB interface

An APB bus is instantiated inside the Memory Controller.

The Memory Controller is compliant with the slave APB interface data width of 8 bits.

The APB interface can be used to configure the Memory Controller internal registers (the complete list of registers is provided in paragraph 4.5).

4.3.2 BYPASS INTERFACE

In addition to the AHB/AXI interfaces the Memory Controller provides a direct path to the DDR2 memory array in a *Controller Bypass* mode.

The following signals are provided at the user interface:

- user_ras_n
- user_cas_n
- user_we_n
- user_addr
- user_ba
- user_cs_n
- user_cke
- user_odt
- user_reset_n
- user_rddata_en
- user_dqiv
- user_dqi
- user_wdata_en
- user_dqo
- user_dm

When using this interface, signals are transferred directly to the DDR2 memory array without any reformatting inside the Memory Controller, therefore it is the user's responsibility to insure that the signals are in conformance with the applicable DDR2 memory datasheets/Detail Specification.

4.3.3 DFI INTERFACE

The Memory Controller implements a DDR PHY Interface (DFI) compatible to DFI 2.1. The DFI is a standardized interface that defines the connectivity between a DDR memory controller and a DDR physical interface (PHY) for DDR1, DDR2, LPDDR2 and DDR3.

PHY IP is available from 3D PLUS, supporting multiple targets (see paragraph 8)

4.4 MEMORY CONTROLLER GENERICS/PARAMETERS AND PORTS

The Memory Controller contains the ports defined in Table 4 to Table 7.

The Memory Controller contains the generics/parameters defined in Table 8.

Name	Direction	Comments
SysClk	In	Main input clock used for all of the RIMC (except the DFI interface)
DFIClk	In	Input clock used for DFI interface. Can be SysClk, 2* SysClk or 4* SysClk frequency
Rst_N	In	Input Reset - synchronous to SysClk, active LOW
DFIRst_N	In	Input Reset - synchronous to DFIClk, active LOW
SCRUB_EN	In	0: Scrubbing is disabled 1: Scrubbing is enabled
REF_MODE	In	0: Normal refresh 1: Refresh timing is divided by 2

Table 4: Memory Controller Core Ports

Name	Direction	Comments
Ahbsi(NB_AHB_SLV-1:0)	In	AHB slave input array of record type
Ahbsi(NB_AHB_SLV-1:0)	Out	AHB slave output array of record type
AXI_aw_out(NB_AXI_SLV-1:0)	In	AXI write address channel input array of record type
AXI_aw_in(NB_AXI_SLV-1:0)	Out	AXI write address channel output array of record type
AXI_w_out(NB_AXI_SLV-1:0)	In	AXI write data channel input array of record type
AXI_w_in(NB_AXI_SLV-1:0)	Out	AXI write data channel output array of record type
AXI_b_out(NB_AXI_SLV-1:0)	Out	AXI write response channel input array of record type
AXI_b_in(NB_AXI_SLV-1:0)	In	AXI write response channel output array of record type
AXI_ar_out(NB_AXI_SLV-1:0)	In	AXI read address channel input array of record type
AXI_ar_in(NB_AXI_SLV-1:0)	Out	AXI read address channel output array of record type
AXI_r_out(NB_AXI_SLV-1:0)	Out	AXI read data channel input array of record type
AXI_r_in(NB_AXI_SLV-1:0)	In	AXI read data channel output array of record type
Apbi	In	APB slave input
Apbo	Out	APB slave output

Table 5: Memory Controller AMBA Ports

Name	Direction	Comments
Control Interface		
Dfi_address	Out	DFI address bus
Dfi_bank	Out	DFI bank bus
Dfi_cas_n	Out	DFI column address strobe bus
Dfi_cke	Out	DFI clock enable bus
Dfi_cs_n	Out	DFI chip select bus
Dfi_odt	Out	DFI on-die-termination control bus
Dfi_ras_n	Out	DFI row address strobe bus
Dfi_reset_n	Out	DFI reset bus
Dfi_we_n	Out	DFI write enable bus
Write data interface		
Dfi_wrdata	Out	DFI write data bus
Dfi_wrdata_en	Out	DFI write data and data mask enable
Dfi_wrdata_mask	Out	DFI write data Byte mask
Read data interface		
Dfi_rddata_en	Out	DFI read data enable
Dfi_rddata	In	DFI read data bus
Dfi_rddata_dnv	In	DFI data not valid

Name	Direction	Comments
Dfi_rddata_valid	In	DFI read data valid indicator
Update interface		
Dfi_ctrlupd_req	Out	MC-initiated update request
Dfi_phyupd_ack	Out	PHY-initiated update acknowledge
Dfi_ctrlupd_ack	In	MC-initiated update acknowledge
Dfi_phyupd_req	In	PHY-initiated update request
Dfi_phyupd_type	In	PHY-initiated update select
Status interface		
Dfi_dram_clk_disable	Out	DRAM clock disable
Dfi_freq_ratio	Out	DFI frequency ratio indicator
Dfi_init_complete	In	PHY initialization complete
Training interface		
Dfi_rdlvl_load	Out	Not used for DDR2.
Dfi_rdlvl_cs_n	Out	Not used for DDR2.
Dfi_rdlvl_en	Out	Not used for DDR2.
Dfi_rdlvl_edge	Out	Not used for DDR2.
Dfi_rdlvl_delay_X	Out	Not used for DDR2.
dfi_rdlvl_gate_en	Out	Not used for DDR2.
dfi_rdlvl_gate_delay_X	Out	Not used for DDR2.
dfi_wrlvl_load	Out	Not used for DDR2.
dfi_wrlvl_cs_n	Out	Not used for DDR2.
dfi_wrlvl_strobe	Out	Not used for DDR2.
dfi_wrlvl_en	Out	Not used for DDR2.
dfi_wrlvl_delay_X	Out	Not used for DDR2.
dfi_rdlvl_resp	In	Not used for DDR2.
dfi_rdlvl_mode	In	Not used for DDR2.
dfi_rdlvl_gate_mode	In	Not used for DDR2.
dfi_wrlvl_mode	In	Not used for DDR2.
dfi_wrlvl_resp	In	Not used for DDR2.

Table 6: Memory Controller DFI Ports

Name	Direction	Comments
user_ras_n	In	Row Address Select. Used only in the "Controller Bypass" mode
user_cas_n	In	Column Address Select. Used only in the "Controller Bypass" mode

Name	Direction	Comments
user_we_n	In	Write Enable, active LOW. Used only in the "Controller Bypass" mode
user_address	In	Address bus. Used only in the "Controller Bypass" mode
user_bank	In	Bank Address bus. Used only in the "Controller Bypass" mode
user_cs_n	In	Chip Select, active LOW. Used only in the "Controller Bypass" mode
uer_cke	In	Clock Enable. Used only in the "Controller Bypass" mode
user_odt	In	On Die Termination. Used only in the "Controller Bypass" mode
user_reset_n	In	Not used for DDR2.
user_rddata_en	In	Read data enable
user_dqiv	Out	Data input valid. Used only in the "Controller Bypass" mode
user_dqi	Out	Data input. Used only in the "Controller Bypass" mode
user_wdata_en	In	Write data enable
user_dqo	In	Data output. Used only in the "Controller Bypass" mode
user_dm	In	Data output mask. Used only in the "Controller Bypass" mode

Table 7: Memory Controller Bypass Ports

Name	Comments	Default value
DRAM_TYPE	Shall be set to "DDR2"	"DDR2"
RTT_NOM	Nominal ODT termination value	75
AL	Additive Latency option	0
OUTPUT_DRV	DDR2/DDR3 output drive.	"HIGH"
HDMAX	Width of the user AMBA busses	32
GSYNCRST	0: Asynchronous reset 1: Synchronous reset	1
G_RAM_INST	0: RAM is inferred 1: RAM is instantiated. In this configuration, the VHDL file ip/tpram_inst.vhd shall be updated by the customer	0
USE_DFF	0: Use block ram inside RIMC 1: Use DFF instead of block RAM 2: Automatic selection. DFF will be used for memories less than 600 bits	0

Name	Comments	Default value
ECC_EN	0: No ECC for internal RAMs 1: Hamming ECC for internal RAMs	0
ENDIANNESS	Endianness of the AHB bus. Can be set to BIG_ENDIAN or LITTLE_ENDIAN. This generic is not meaningful for AXI bus.	BIG_ENDIAN
SIMU	Set to 1 for simulation only	0
NB_AHB_SLV	Number of slave AHB busses. Shall be between 0 and 8.	1
NB_AXI_SLV	Number of slave AXI busses. Shall be between 0 and 8.	1
tphy_wrddata		0
tphy_wrlat	Number of DFI clock cycles between a write command and the wrdata_en	0
trddata_en		0
TWR_PS	Write recovery time, in ps	15000
TWTR_PS	Write to read timing, in ps	7500
TRTP_PS	Internal READ to PRECHARGE delay, in ps	7500
TRFC_PS	REFRESH to ACTIVE command interval, in ps	127500
CLK_PERIOD	SysClk clock period, in ps	3000
nCK_PER_CLK	Ratio between SysClk and DDR2 memory clock (see Table 1 for allowed values)	1
CAS_LAT	Read CAS latency. In number of clock cycles	5
TWO_T_TIME_EN	Control to DDR2 can be performed in "2T" mode 0: Mode "1T" 1: Mode "2T"	0
SLOT_NUM	This generic defines the slot/phase where the DFI command is applied in the DFI bus. It should be set to 0 for all targets except Xilinx 7-series FPGA. It shall be in the range from 0 to nCK_PER_CLK-1	0
BURST_TYPE	0=sequential, 1=interleaved	0
BURST_LEN	Shall be 4 or 8	8
CS_NUM	Number of ranks. Shall be set to 1, 2, 4 or 8	1
BANK_WIDTH	Number of banks	3
ROW_WIDTH	Number of rows	14

Name	Comments	Default value
COL_WIDTH	Number of columns	10
DATA_WIDTH	Data width, without ECC. See Table 1 for authorized values.	16
ECC_WIDTH	Width of the ECC	6
DQ_WIDTH	Width of the global DQ bus (DQ_WIDTH shall be DATA_WIDTH+ECC_WIDTH, rounded up to the next multiple of 8)	24

Table 8: Memory Controller Generic/Parameter list

4.5 MEMORY CONTROLLER REGISTERS

The Memory Controller contains the registers defined in Table 9. Details are given from Table 10 to Table 24.

Registers	Address
ECC_DErr_Reg0	0x00
ECC_DErr_Reg1	0x01
ECC_SErr_Reg0	0x02
ECC_SErr_Reg1	0x03
ECC_DErr_Clr	0x04
ECC_SErr_Clr	0x05
Bypass_Reg	0x06
Init_Pad_Reg	0x07
Init_Pad_Sts	0x08
Init_Pad_Ctl	0x09
Scrubbing_Reg0	0x0A
Scrubbing_Reg1	0x0B
ScrubEn_Reg	0x0C
Scrub_Ctl	0x0D
CorEn_Reg	0x0E
CorBeat_Reg	0x0F
CorVec_Reg0	0x10
CorVec_Reg1	0x11
CorVec_Reg2	0x12
CorVec_Reg3	0x13
CorVec_Reg4	0x14
CorVec_Reg5	0x15
CorVec_Reg6	0x16
CorVec_Reg7	0x17
CorVec_Reg8	0x18
CorVec_Reg9	0x19
CorVec_Reg10	0x1A
CorVec_Reg11	0x1B
ScrubAd_Sts0	0x1C
ScrubAd_Sts1	0x1D
ScrubAd_Sts2	0x1E
ScrubAd_Sts3	0x1F
Version_Sts	0x20

Table 9: RIMC registers list

Bits	Field Name	Comments	R/W	Reset value
15-0	CNT	Uncorrectable ECC counter	R	0

Table 10: ECC_DErr_Reg0 (Most Significant Byte) and ECC_DErr_Reg1 (Least Significant Byte)

Bits	Field Name	Comments	R/W	Reset value
15-0	CNT	Correctable ECC counter	R	0

Table 11: ECC_SErr_Reg0 and ECC_SErr_Reg1

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	CLR	0: No effect 1: Clear ECC_DErr_Reg registers	W	0

Table 12: ECC_DErr_Clr register

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	CLR	0: No effect 1: Clear ECC_SErr_Reg registers	W	0

Table 13: ECC_SErr_Clr register

Bits	Field Name	Comments	R/W	Reset value
7-4	-	Reserved	R	0
3	-	Reserved. Do NOT modify	R/W	1
2-1	MODE	b00: SEFI protection = STRONG b01: SEFI protection = SIMPLE b10: No SEFI protection b11: Reserved	R/W	0
0	BYP	0: Normal mode 1: Bypass mode. In this mode the only available user interface is the bypass interface	R/W	0

Table 14: Bypass_Reg register

Bits	Field Name	Comments	R/W	Reset value
7-0	VAL	Byte value used for initialization of the entire memory array.	R/W	0

Table 15: Init_Pad_Reg register

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	STS	0: Padding is in IDLE 1: Padding is in progress	R	0

Table 16: Init_Pad_Sts register

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	START	0: No effect 1: Begin the padding of the entire memory array	W	0

Table 17: Init_Pad_Ctl register

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	EN	0: Scrubbing disabled 1: Scrubbing enabled	R/W	0

Table 18: ScrubEn_Reg register

Bits	Field Name	Comments	R/W	Reset value
15-0	FREQ	Register used to select the frequency of the scrubbing. 1 DDR Burst performed each FREQ SysClk clock cycles. <u>Note:</u> This value shall be greater than or equal to 256	R/W	0x0100

Table 19: Scrubbing_Reg0 and Scrubbing_Reg1

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	RST	0: No effect 1: Reset ScrubAd_Sts0 to ScrubAd_Sts3 registers	W	0

Table 20: Scrub_Ctl register

Bits	Field Name	Comments	R/W	Reset value
31-0	AD	Address of the memory in which the scrubbing detected the 1 st error	R	0

Table 21: ScrubAd_Sts0 to ScrubAd_Sts3

Bits	Field Name	Comments	R/W	Reset value
7-1	-	Reserved	R	0
0	EN	Enable the corruption of data. Used to test the correct behavior of the ECC mechanism	R/W	0

Table 22: CorEn_Reg register

Bits	Field Name	Comments	R/W	Reset value
95-0	COR_BIT	Bit to corrupt (used only when CorEn_Reg register = 0x01)	R/W	0

Table 23: CorVec_Reg0 to CorVec_Reg11

Bits	Field Name	Comments	R/W	Reset value
7-3 ⁽¹⁾	-	Reserved	R	0
2-0 ⁽¹⁾	COR_BEAT	Beat to corrupt (used only when CorEn_Reg register = 0x01)	R/W	0

Table 24: CorBeat_Reg

Note 1: The width of COR_BEAT field is $\log_2(2 \times nCK_PER_CLK)$, which means:

- COR_BEAT(0:0) when $nCK_PER_CLK=1$
- COR_BEAT(1:0) when $nCK_PER_CLK=2$
- COR_BEAT(2:0) when $nCK_PER_CLK=4$

5 RIMC (MEMORY CONTROLLER + PHY)

The Physical layer IP (PHY) is dependant of the FPGA/ASIC technology being used. The following PHY are available for use inside the RIMC:

- Xilinx Virtex-5 FPGA
- Xilinx 7-series FPGA
- Microsemi RTG4 FPGA

5.1 RIMC INTERFACES

The RIMC provides the following interfaces:

- The AMBA interfaces (already described in paragraph 4.3.1)
- The Bypass interface (already described in paragraph 4.3.2)
- The DDR2 memory interface
- The Xilinx MIG interface

5.1.1 DDR2 INTERFACE

The RIMC is compliant to the JEDEC DDR2 memory interface specification.

5.1.2 XILINX MIG INTERFACE

A specific MIG interface is present at the UI of the RIMC to allow a direct replacement of a MIG DDR controller from Xilinx with the RIMC.

A bridge is provided inside of the RIMC to convert the MIG interface into a standard AXI interface.

5.2 RIMC GENERICS/PARAMETERS AND PORTS

The RIMC contains the ports defined in Table 25 to Table 29.

The RIMC contains the generics defined in Table 30.

Name	Direction	Comments
ClkIn	In	Input clock. The "Memory controller" and PHY input clocks are derivated from this clock to operate with the nCK_PER_CLK generic.
idly_clk_200	In	Input clock at 200 MHz. This clock is used only for Xilinx FPGAs.
Rst_N	In	Input reset, active LOW
clk0_o	Out	User output clock. This clock shall be used for User Interfaces (AHB, AXI, APB, Bypass)
rst0_n_o	Out	Output reset, synchronous to $clk0_o$. Active LOW
SCRUB_EN	In	0: Scrubbing is disabled 1: Scrubbing is enabled
REF_MODE	In	0: Normal refresh 1: Refresh timing is divided by 2

Table 25: RIMC Core Ports

Name	Direction	Comments
Ahbsi(NB_AHB_SLV-1:0)	In	AHB slave input array of record type
Ahbso(NB_AHB_SLV-1:0)	Out	AHB slave output array of record type
AXI_aw_out(NB_AXI_SLV-1:0)	In	AXI write address channel input array of record type
AXI_aw_in(NB_AXI_SLV-1:0)	Out	AXI write address channel output array of record type
AXI_w_out(NB_AXI_SLV-1:0)	In	AXI write data channel input array of record type
AXI_w_in(NB_AXI_SLV-1:0)	Out	AXI write data channel output array of record type
AXI_b_out(NB_AXI_SLV-1:0)	Out	AXI write response channel input array of record type
AXI_b_in(NB_AXI_SLV-1:0)	In	AXI write response channel output array of record type
AXI_ar_out(NB_AXI_SLV-1:0)	In	AXI read address channel input array of record type
AXI_ar_in(NB_AXI_SLV-1:0)	Out	AXI read address channel output array of record type
AXI_r_out(NB_AXI_SLV-1:0)	Out	AXI read data channel input array of record type
AXI_r_in(NB_AXI_SLV-1:0)	In	AXI read data channel output array of record type
Apbi	In	APB slave input
Apbo	Out	APB slave output

Table 26: RIMC AMBA Ports

Name	Direction	Comments
ddr_ck	Out	DDR clock
ddr_ck_n	Out	DDR negative clock
ddr_addr	Out	DDR address bus
ddr_ba	Out	DDR bank bus
ddr_cas_n	Out	DDR column address strobe bus
ddr_cke	Out	DDR clock enable bus
ddr_cs_n	Out	DDR chip select bus
ddr_odt	Out	DDR on-die-termination control bus
ddr_ras_n	Out	DDR row address strobe bus
ddr_rst_n	Out	DDR reset bus. Not used for DDR2
ddr_dm	Out	DDR data mask
ddr_dq	Inout	DDR data
ddr_dqs	Inout	DDR data strobe
ddr_dqs_n	Inout	DDR negative data strobe
ddr_we_n	Out	DDR write enable

Table 27: RIMC DDR Ports

Name	Direction	Comments
app_af_cmd	In	b000 for Write command b001 for Read command Other combinations are invalid
app_af_addr	In	Gives information about the address of the memory location to be accessed. This bus contains the bank address, the row address, and the column address
app_af_wren	In	Write enable to the User Address FIFO. This signal should be synchronized with the app_af_addr and app_af_cmd signals.
app_af_afull	In	Almost Full status of the Address FIFO. When this signal is asserted, the user can write 12 more locations into the FIFO.
app_wdf_data	In	User input data. It should contain the fall data and the rise data. Rise data = app_wdf_data[DQ_WIDTH-1: 0] Fall data = app_wdf_data[2*DQ_WIDTH-1: DQ_WIDTH]
app_wdf_mask_data	In	User mask data. It should contain the data mask information for both rise and fall data. Rise mask data = app_wdf_mask_data[DM_WIDTH-1: 0] Fall mask data = app_wdf_mask_data[2*DM_WIDTH-1: DM_WIDTH]
app_wdf_wren	In	Write enable for the User Write FIFO. This signal should be synchronized with the app_wdf_data and app_wdf_mask_data signals.
app_wdf_afull	Out	Almost Full status of the User Write FIFO. When this signal is asserted, the user can write 12 more locations into the FIFO.
rd_data_valid	Out	Status signal indicating read data is valid on the read data bus.
rd_data_fifo_out	Out	Read data from the memory.

Table 28: RIMC MIG ports

Name	Direction	Comments
user_ras_n	In	Row Address Select. Used only in the "Controller Bypass" mode
user_cas_n	In	Column Address Select. Used only in the "Controller Bypass" mode
user_we_n	In	Write Enable, active LOW. Used only in the "Controller Bypass" mode
user_address	In	Address bus. Used only in the "Controller Bypass" mode
user_bank	In	Bank Address bus. Used only in the "Controller Bypass" mode

Name	Direction	Comments
user_cs_n	In	Chip Select, active LOW. Used only in the "Controller Bypass" mode
uer_cke	In	Clock Enable. Used only in the "Controller Bypass" mode
user_odt	In	On Die Termination. Used only in the "Controller Bypass" mode
user_reset_n	In	Not used for DDR2.
user_rddata_en	In	Read data enable
user_dqiv	Out	Data input valid. Used only in the "Controller Bypass" mode
user_dqi	Out	Data input. Used only in the "Controller Bypass" mode
user_wdata_en	In	Write data enable
user_dqo	In	Data output. Used only in the "Controller Bypass" mode
user_dm	In	Data output mask. Used only in the "Controller Bypass" mode

Table 29: RIMC Bypass Ports

Name	Comments	Default value
BA_REPLICATION	Replication of bus ddr_ba. For example, if set to 2, ddr_ba(BANK_WIDTH-1:0) and ddr_ba(2*BANK_WIDTH-1:BANK_WIDTH) outputs the same value	1
ADDR_REPLICATION	Replication of bus ddr_addr	1
CMD_REPLICATION	Replication of signals ddr_ras_n, ddr_cas_n, ddr_we_n and ddr_rst_n	1
SYSClk_TYPE	Define if a clock buffer shall be added to the SysClk input clock Shall be set to "SINGLE_ENDED" or "NO_BUFFER"	"SINGLE_ENDED"
REFCLK_TYPE	Define if a clock buffer shall be added to the idly_clk_200 input clock Shall be set to "SINGLE_ENDED" or "NO_BUFFER"	"SINGLE_ENDED"
BANK_TYPE	Used only for Xilinx 7-series PHY. Shall be set to "HP_IO", "HPL_IO", "HR_IO" or "HRL_IO"	"HP_IO"
DATA_IO_PRIM_TYPE	Used only for Xilinx 7-series PHY. Shall be set to "HP_LP", "HR_LP" or "DEFAULT"	"HP_LP"
DRAM_TYPE	Shall be set to "DDR2"	"DDR2"
HDMAX	Width of the user AMBA busses	32
GSYNCRST	0: Asynchronous reset 1: Synchronous reset	1

Name	Comments	Default value
G_RAM_INST	0: RAM is inferred 1: RAM is instantiated. In this configuration, the VHDL file ip/tpam_inst.vhd shall be updated by the customer	0
USE_DFF	0: Use block ram inside RIMC 1: Use DFF instead of block RAM 2: Automatic selection. DFF will be used for memories less than 600 bits	0
ECC_EN	0: No ECC for internal RAMs 1: Hamming ECC for internal RAMs	0
FPGA_SPEED_GRADE	Speed Grade of the FPGA (Used only for Xilinx Virtex-5 FPGA)	2
ENDIANNESS	Endianness of the AHB bus. Can be set to BIG_ENDIAN or LITTLE_ENDIAN. This generic is not meaningful for AXI bus.	BIG_ENDIAN
NB_AHB_SLV	Number of slave AHB busses. Shall be between 0 and 8.	1
NB_AXI_SLV	Number of slave AXI busses. Shall be between 0 and 8.	1
SIMU	Set to 1 for simulation only	0
BURST_LEN	Shall be 4 or 8	8
CLKIN_PERIOD	Input clock period, in ps	3000
tCK	Memory clock period, in ps	3000
nCK_PER_CLK	Ratio between SysClk and DDR2 memory clock (see Table 1 for allowed values)	1
CAS_LAT	Read CAS latency. In number of clock cycles	5
TWO_T_TIME_EN	Control to DDR2 can be performed in "2T" mode 0: Mode "1T" 1: Mode "2T"	0
TWR_PS	Write recovery time, in ps	15000
TWTR_PS	Write to read timing, in ps	7500
TRTP_PS	Internal READ to PRECHARGE delay, in ps	7500
TRFC_PS	REFRESH to ACTIVE command interval, in ps	127500
RTT_NOM	Nominal ODT termination value	"75"
RTT_WR	Shall be set to "OFF", "60" or "120"	"120"
OUTPUT_DRV	DDR2/DDR3 output drive.	"HIGH"
AL	Additive Latency option	"0"

Name	Comments	Default value
phy_config	Used only for Xilinx 7-series PHY	-
CS_NUM	Number of ranks. Shall be set to 1, 2, 4 or 8	1
CS_WIDTH	Number of CS_N bits	1
CKE_WIDTH	Number of CKE bits	1
ODT_WIDTH	Number of ODT bits	1
BANK_WIDTH	Number of banks	3
ROW_WIDTH	Number of rows	14
COL_WIDTH	Number of columns	10
CLK_WIDTH		
DATA_WIDTH	Data width, without ECC. See Table 1 for authorized values.	16
ECC_WIDTH	Width of the ECC	6
DQ_WIDTH	Width of the DQ bus	24
DM_WIDTH	Data mask width	3
DQS_WIDTH	Data strobe width	3

Table 30: RIMC Generic list

6 RIMC PERFORMANCES

6.1 MAXIMUM FREQUENCY

	Memory Controller	Physical Layer
Xilinx Virtex 5	100 MHz (Speed Grade -1) ⁽¹⁾ 125 MHz (Speed Grade -2 and -3) ⁽¹⁾	333 MHz
Xilinx Kintex 7	333 MHz	333 MHz
Xilinx Virtex 5 QV (Space Grade)	83 MHz ⁽¹⁾	166 MHz
Microsemi RTG4	62.5 MHz ⁽¹⁾	200 MHz

Note 1: For these targets, the memory controller cannot run at the same frequency. The generic nCK_PER_CLK shall be chosen accordingly.

Example memory configuration:

	Memory Configuration <i>Global Bus Width(Data + ECC)</i>	Frequency	Validation method
Xilinx FPGA <i>Virtex 5 & Kintex 7</i>	8 (8+0)	333 MHz	Board
	16 (8+5)	333 MHz	Board
	24 (16 +6)	333 MHz	Board
	32 (32+0)	333 MHz	Board
	40 (32 +7)	333 MHz	Board
	48 (32+16)	333 MHz	Board
	64 (32+32)	333 MHz	Simulation
	72 (64+8)	333 MHz	Simulation
	96 (64+32)	333 MHz	Simulation
Microsemi FPGA <i>RTG4</i>	8 (8+0)	200MHz	Board
	16 (8+5)	200MHz	Board
	24 (16 +6)	200MHz	Board
	32 (32+0)	200MHz	Board
	40 (32 +7)	200MHz	Simulation
	48 (32 + 16)	200MHz	Simulation

Example configuration of generic nCK_PER_CLK:

Customer need	RIMC configuration	Memory Controller frequency
200 MHz, 400 Mbits/s	nCK_PER_CLK = 4	50 MHz
125 MHz, 250 Mbits/s	nCK_PER_CLK = 2	62.5 MHz
125 MHz, 250 Mbits/s	nCK_PER_CLK = 4	31.25 MHz

6.2 IP SIZE

The following sizes are given for the complete RIMC IP composed of both the Memory Controller and the PHY for a given FPGA target.

Table 31 and Table 32 give the estimated sizes for different FPGA platforms based on the following Hypothesis :

- DDR2 48 bits (32 data + 16 ECC)
- 2 user AMBA interfaces, each one supporting 64 bits
- nCK_PER_CLK = 2 for Kintex 7 and RTG4
- nCK_PER_CLK = 1 for Virtex 5

The precise IP Size depends on the configuration.

FPGA	Slice registers	Slice LUTs
Xilinx Virtex 5	3570	3892
Xilinx Kintex 7	8615	8217

Table 31: Xilinx resource usage

Type	Used
4LUT	5000
DFF	5000
Logic element	7000

Table 32: Microsemi RTG4 resource usage

7 DELIVERABLES

The RIMC IP is delivered with the following directory structure:

- 3DIPMC0700-1:
 - o source_scr: This directory contains all of the VHDL files for the Memory Controller IP core as well as PHY cores and RIMCs.
 - ip: This directory contains all of the VHDL files of the Memory Controller core. These files are obfuscated.
 - wrapper: This directory contains the VHDL files needed to connect the Memory Controller IP core and the physical layer
 - ddr2_v5_phy: Physical layer for a Xilinx Virtex5 FPGA
 - ddr2_7series_phy: Physical layer for a Xilinx Kintex7 or Virtex7 FPGA
 - ddr2_rtg4_phy: Physical layer for a Microsemi RTG4 FPGA
 - o routage: This directory contains Xilinx constraint files used only for examples, since the final constraint file depends on the user pinout.
 - o impact_v5: Contains a batch file (implement_example.sh) which can be used to test the synthesis of the RIMC IP for a Virtex 5 FPGA
 - o impact_7series: Contains a batch file (implement.sh) which can be used to test the synthesis of the RIMC IP for a Kintex 7 FPGA
 - o doc: Contains the datasheet of the RIMC

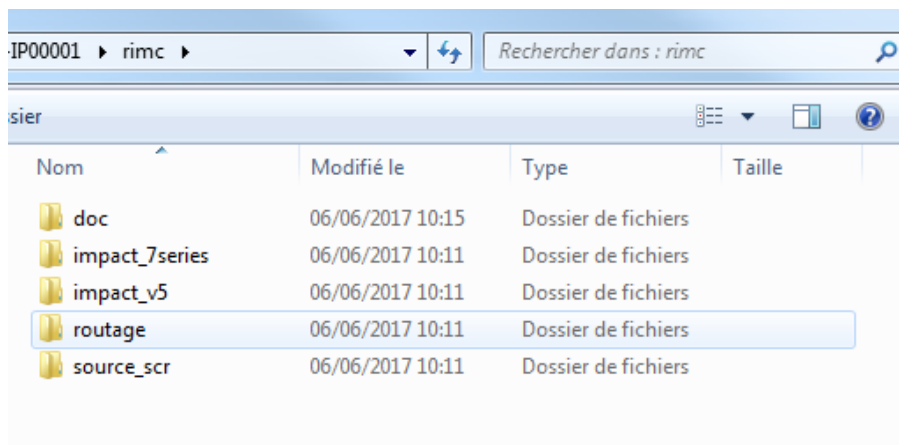


Figure 5: Directory architecture of the deliverables

8 TARGET COMPATIBILITY

The RIMC IP core is delivered as high level VHDL source code. It is compatible with a wide range of ASICs and FPGAs.

To date hardware validation has been performed with Xilinx and MicroSemi FPGAs.



Radiation Intelligent Memory Controller DDR2 SDRAM Controller IP Core 3DIPMC0700-1

9 PART NUMBER / ORDER INFORMATION

3DIPMC0700-1

Main Sales Office

FRANCE	3D PLUS 408, rue Hélène Boucher ZI. 78532 BUC Cedex	Tel : 33 (0)1 30 83 26 50	Fax : 33 (0)1 39 56 25 89	Web : www.3d-plus.com e-mail : sales@3d-plus.com	DISTRIBUTOR
USA	3D PLUS USA, Inc 151 Callan Avenue, Suite 310 San Leandro, CA 94577	Tel : (510) 824-5591	Tel : (510) 824-5591	e-mail : sales@3d-plus.com	

10 REVISION HISTORY

Rev. 9, July 2021

- Remove the Note 2 in paragraph 6.1

Rev. 8, October 2019

- Update available and default values for BANK_TYPE generic
- Update Bypass_Reg register
- Update OUTPUT_DRV generic definition
- RTG4: Remove restriction that only IO banks 0 and 9 should be used for RIMC.
- Add SLOT_NUM generic for Memory Controller
- Remove FREQ_RATIO generic

Rev. 7, January 2019

- Table 19: Update Scrubbing_Reg0 reset value, and add a note
- Table 24: Add a note regarding CorBeat_Reg register width
- Add ECC_EN and G_RAM_INST generics
- The generic USE_DFF can now have the value 2

Rev. 6, February 2018

- Update Figure 1
- Add BA_REPLICATION, ADDR_REPLICATION, CMD_REPLICATION, CLKIN_PERIOD, tCK, CAS_LAT, TWO_T_TIME_EN, TWR_PS, TWTR_PS, TRTP_PS, CLK_WIDTH, DM_WIDTH, DQS_WIDTH, FPGA_SPEED_GRADE generics to RIMC in Table 30
- Add tphy_wrdata, tphy_wrlat, trddata_en, TWR_PS, TWTR_PS, TRTP_PS, CLK_PERIOD, CAS_LAT, TWO_T_TIME_EN, BURST_TYPE generics to memory controller in Table 8
- Add Table 21 to 24 with description of Scrub_Ctl, CorEn_Reg, CorVec_Regx, CorBeat_Reg registers
- Remove memory controller register Table EDACConf_Reg register
- IP size for RTG4 is given with nCK_PER_CLK generic equal to 2

Rev. 5, October 2017

- Update syntax on the entire document
- Precise Data width
- Delete memory Redundancy support
- Update Xilinx MIG interface information
- Add details to support Miconsemi RTG4 FPGA
- Delete DDR memory interface subsystem figure
- Update bypass interface signals
- Table 8 updated from RIMC Generic list to Memroy Controller Generic/Parameter list
- Update Chapter5.2 from WRAPPER GENERICS AND PORTS to RIMC GENERICS/PARAMETERS AND PORTS
- Add Chapter6 RIMC Performance

Rev. 4, June 2017

- Paragraphs 5 & 6: Introduce RIMC and RIMC+ PHY IP cores in 2 seperated Paragraphs
- Paragraph 4: figure1 updated
- Paragraph 5.5: register list table added and delete DDR_SEL register
- Paragraph 4.2.3: Remove cold redundancy management

- Paragraph 5: Remove APB_DIS generic
- Paragraph 7: IP Size updated

Rev. 3, February 2017

- Figure 1 updated to add MIG interface and Bypass interface
- Paragraph 4.1 Initialization pin updated
- Table1 updated with DDR2 component width
- Paragraph 4.2 Data path example was deleted
- Paragraph 6 RIMC Generics and Ports updated
- Paragraph 7 RIMC Registers updated
- Paragraph 8 IP Size added

Rev. 2, July 2016

- Initial datasheet release

Rev. 1, March 2016

- Initial flyer release